

1. General description

Silicon Carbide Schottky diode in a TO263-2L (D2PAK) plastic package, designed for high frequency switched-mode power supplies.



AEC - Q101 Qualified



2. Features and benefits

- New 6th Generation Technology
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Forward Surge Capability I_{FSM}
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- AEC-Q101 qualified

3. Applications

- EV On Board Chargers
- EV DC-DC converters
- Other EV HV systems

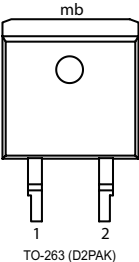
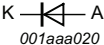
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage			650			V
I_F	continuous forward current	$T_{mb} \leq 143\text{ °C}$, DC; Fig. 2		30			A
T_j	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	$I_F = 30\text{ A}$; $T_j = 25\text{ °C}$; Fig. 5		-	1.26	1.40	V
		$I_F = 30\text{ A}$; $T_j = 150\text{ °C}$; Fig. 5		-	1.35	1.55	V
Dynamic characteristics							
Q_r	recovered charge	$I_F = 30\text{ A}$; $di_F/dt = 500\text{ A}/\mu\text{s}$; $V_R = 400\text{ V}$; $T_j = 25\text{ °C}$; Fig. 7		-	72	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-263 (D2PAK)</p>	
2	A	anode		
mb	K	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC6D30650BT2-A	TO263-2L	WNSC6D30650BT2-A6J	Reel	800	TO263N-2L	14-Oct-2022

7. Marking

Table 4. Marking codes

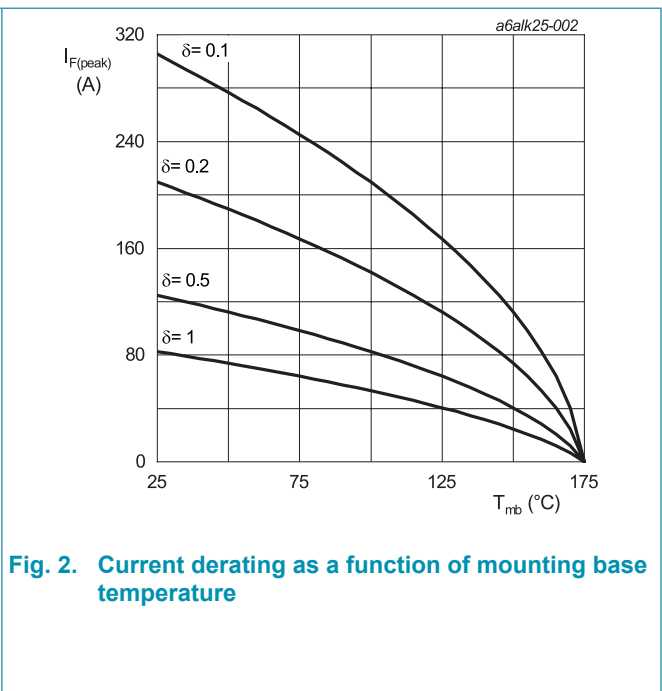
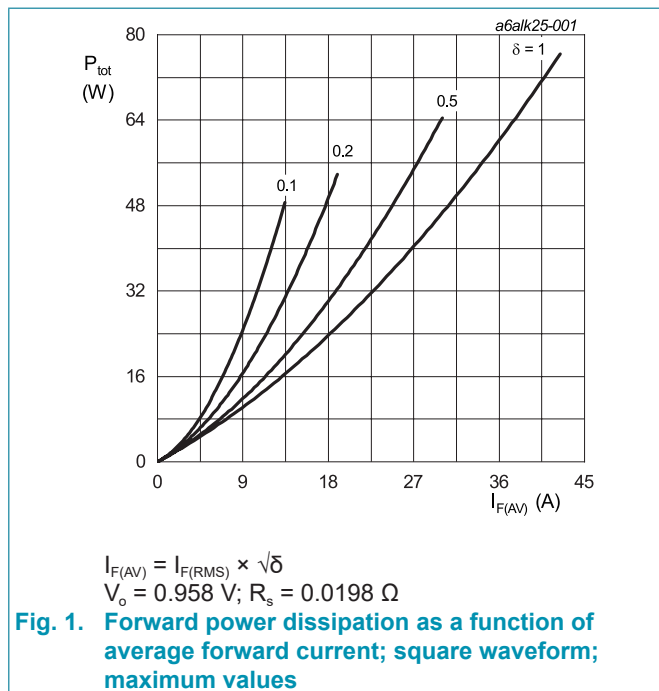
Type number	Marking codes
WNSC6D30650BT2-A	WNSC6D 30650BT2-A

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			650	V
V_{RWM}	crest working reverse voltage			650	V
V_R	reverse voltage	DC		650	V
I_F	continuous forward current	$T_{mb} \leq 143\text{ }^\circ\text{C}$, DC; Fig. 2		30	A
		$T_{mb} \leq 125\text{ }^\circ\text{C}$, DC; Fig. 2		40	A
		$T_{mb} \leq 25\text{ }^\circ\text{C}$, DC; Fig. 2		83	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 125\text{ }^\circ\text{C}$; square-wave pulse		64	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse		200	A
		$t_p = 10\text{ }\mu\text{s}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; square-wave pulse		1100	A
I^2t	I^2t for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; $t_p = 10\text{ ms}$		200	A^2s
T_{stg}	storage temperature			-55 to 175	$^\circ\text{C}$
T_j	junction temperature			-55 to 175	$^\circ\text{C}$



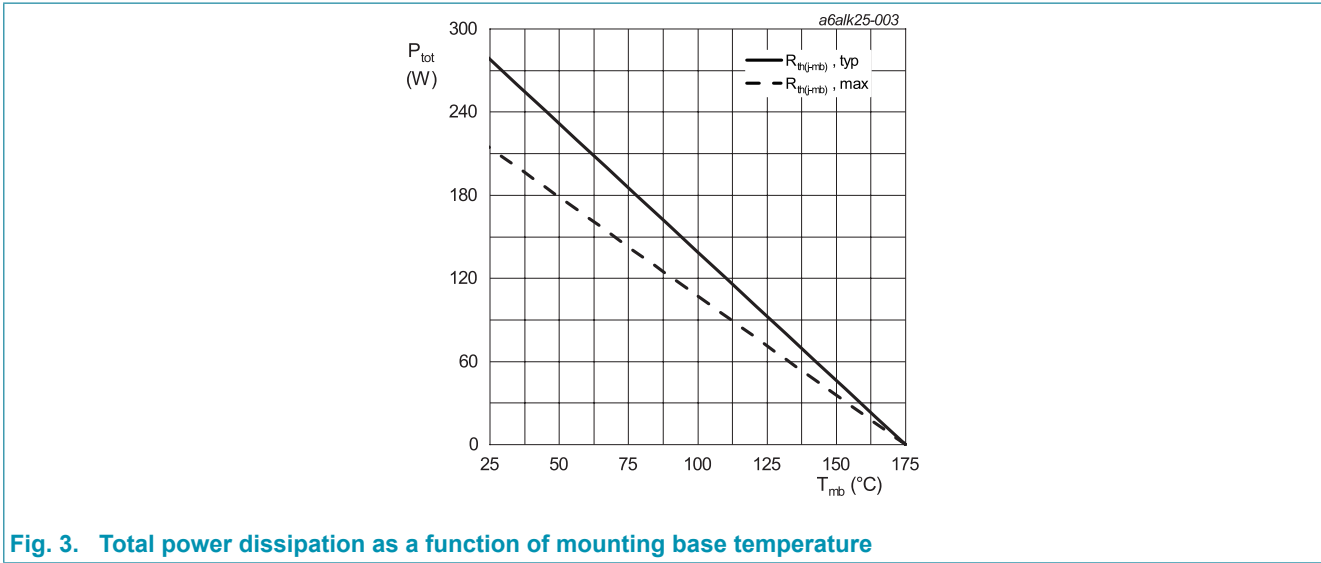


Fig. 3. Total power dissipation as a function of mounting base temperature

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4		-	0.54	0.7	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

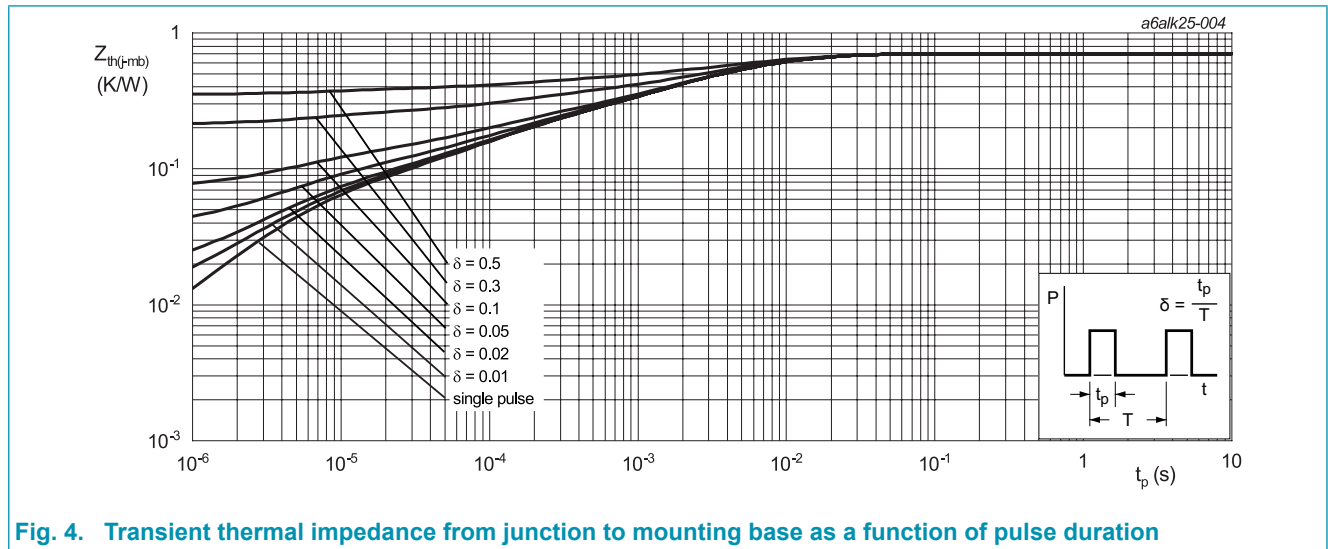
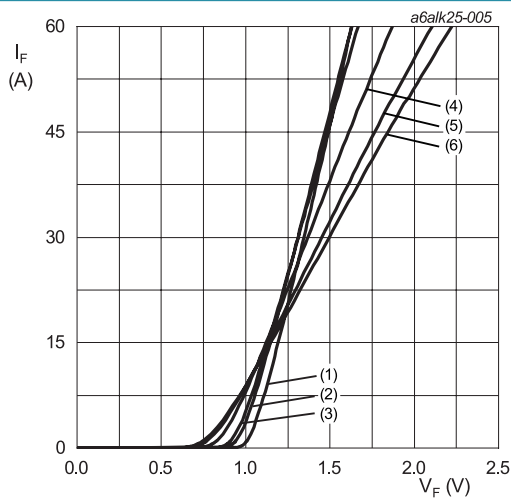


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	$I_F = 30\text{ A}; T_J = 25\text{ }^\circ\text{C}; \text{Fig. 5}$		-	1.26	1.40	V
		$I_F = 30\text{ A}; T_J = 150\text{ }^\circ\text{C}; \text{Fig. 5}$		-	1.35	1.55	V
		$I_F = 30\text{ A}; T_J = 175\text{ }^\circ\text{C}; \text{Fig. 5}$		-	1.40	1.60	V
I_R	reverse current	$V_R = 650\text{ V}; T_J = 25\text{ }^\circ\text{C}; \text{Fig. 6}$		-	2	150	μA
		$V_R = 650\text{ V}; T_J = 175\text{ }^\circ\text{C}; \text{Fig. 6}$		-	30	600	μA
Dynamic characteristics							
Q_r	recovered charge	$I_F = 30\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}; T_J = 25\text{ }^\circ\text{C}; \text{Fig. 7}$		-	72	-	nC
C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 1\text{ V}; T_J = 25\text{ }^\circ\text{C}$		-	1466	-	pF
		$f = 1\text{ MHz}; V_R = 300\text{ V}; T_J = 25\text{ }^\circ\text{C}$		-	154	-	pF
		$f = 1\text{ MHz}; V_R = 600\text{ V}; T_J = 25\text{ }^\circ\text{C}$		-	141	-	pF
E_{as}	non-repetitive avalanche energy	$I_R = 9\text{ A}; L = 5\text{ mH}; T_{J(\text{init})} = 25\text{ }^\circ\text{C}$		200	-	-	mJ



$V_o = 0.958\text{ V}; R_s = 0.0198\ \Omega$
 (1) $T_J = -55\text{ }^\circ\text{C}$; typical values
 (2) $T_J = 0\text{ }^\circ\text{C}$; typical values
 (3) $T_J = 25\text{ }^\circ\text{C}$; typical values
 (4) $T_J = 100\text{ }^\circ\text{C}$; typical values
 (5) $T_J = 150\text{ }^\circ\text{C}$; typical values
 (6) $T_J = 175\text{ }^\circ\text{C}$; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

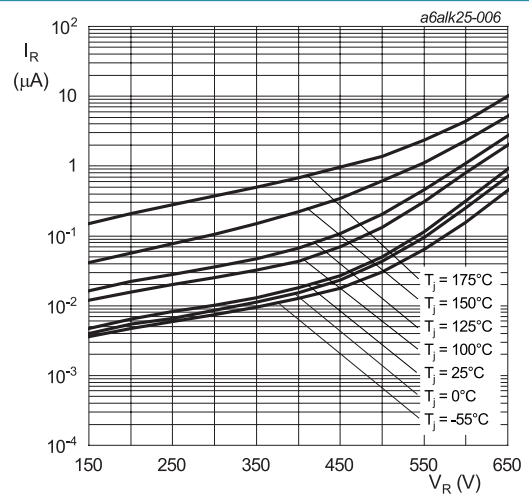


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

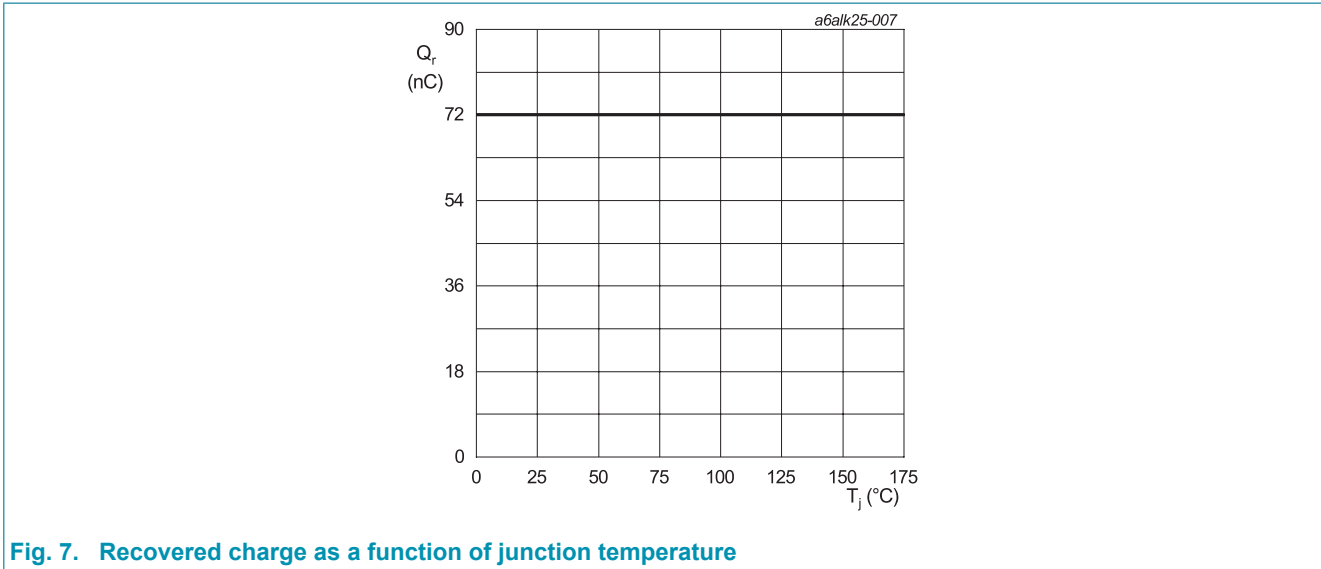
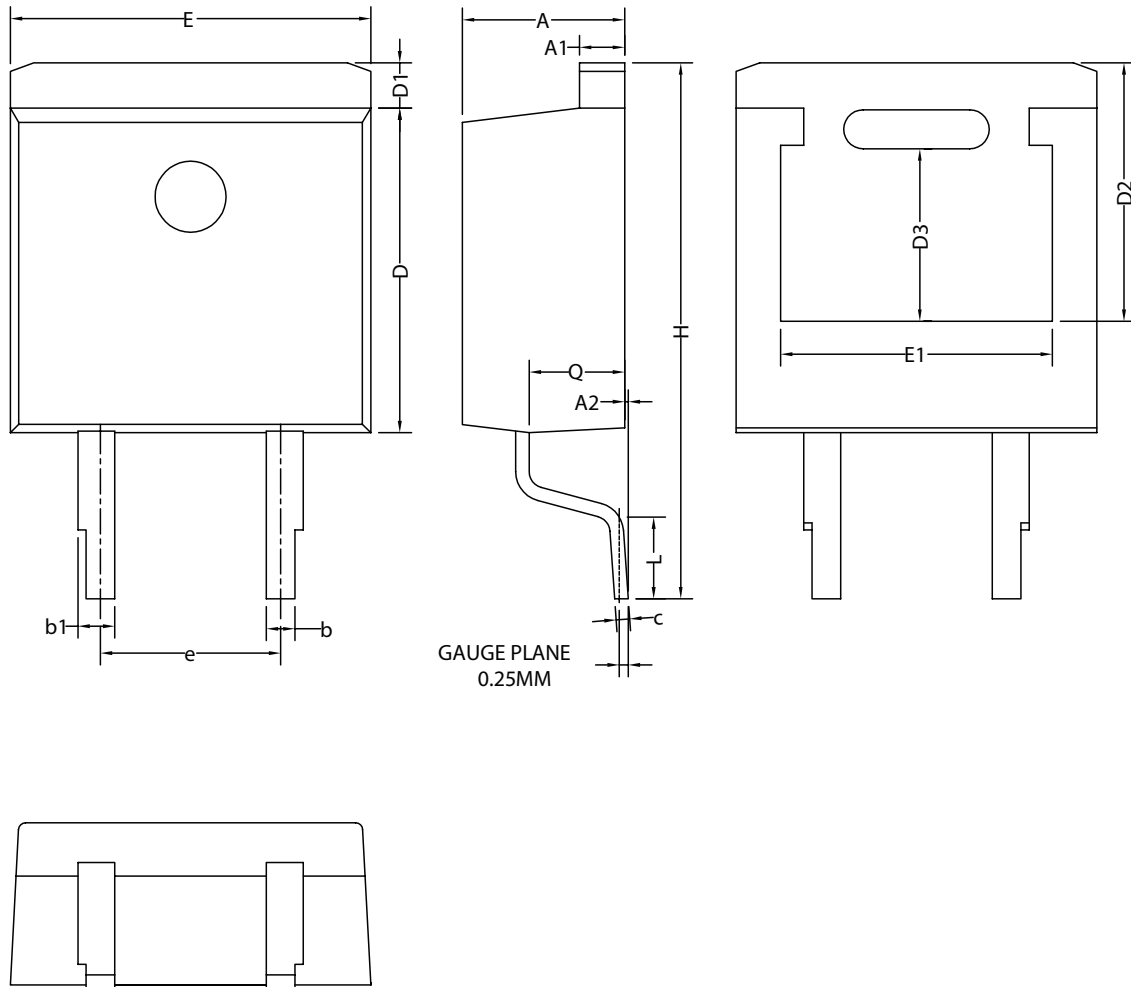


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline

Plastic single-ended surface-mounted package (D2PAK); 2 leads

TO263-2L



Note:
All dimensions do not include mold flash or protrusion.

Unit	A	A1	A2	b	b1	c	D	D1	D2	D3	e	E	E1	H	L	Q
MM	min	4.40	1.22	0.00	0.77	0.95	9.05	1.17	7.13	4.71	5.08 (BSC)	10.00	7.51	14.70	1.95	2.55
	max	4.70	1.36	0.25	0.90	1.15	9.35	1.40	7.43	5.01		10.26	7.81	15.50	2.60	2.79

12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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